

STRESS RELIEF MEMS STRUCTURE AND PACKAGE

ABSTRACT

Stress relief structures and methods that can be applied to MEMS sensors requiring a
5 hermetic seal and that can be simply manufactured are disclosed. The system includes a sensor
having a first surface and a second surface, the second surface being disposed away from the first
surface, the second surface also being disposed away from a package surface and located
between the first surface and the package surface, a number of support members, each support
member extending from the second surface to the package surface, the support members being
10 disposed on and operatively connected to only a portion of the second surface. The support
member are configured to reduce stress produced by package-sensor interaction.

FIG. 2